

ESPI Current Report

Number: 47/2019
Date: 12 November 2019
Company: XTPL S.A., a joint stock company with its registered office in Wrocław

Topic: Establishing cooperation with Hefei BOE Joint Technology Co. Ltd

Legal basis: Article 17(1) MAR - inside information

Contents of the Report: The Management Board of XTPL S.A. (the "Company", the "Issuer") announces that today it has signed an agreement for technology validation with Hefei BOE Joint Technology Co. Ltd with its registered seat in China ("Partner") - subsidiary of one of the leading global producers operating in the display industry based in China

The purpose of the agreement is to confirm parameters of the technology developed and commercialized by the Issuer and to assess the possibility of implementing the technology in the production Partner's processes. The XTPL nanoprinting technology offered to the Partner will be dedicated to obtain transparent conductive mesh which will improve electrical conductivity in new generations of displays. Each party will be responsible for their respective costs, i.e. the Issuer - for the costs of the printing samples on the Partner's substrates and the Partner - for the costs of preparing and sending the substrates for evaluation, costs of advanced analysis of the obtained nanoprints and assessment of the results of technological tests and costs of the reference visits to Issuer's headquarters.

In the opinion of the Company's Management Board executing the Technology Evaluation Agreement is to be considered as inside information because the Partner has declared that if the project produces satisfactory results, the Partner will be ready to start negotiations on the main business assumptions for the commercial cooperation, and therefore there are reasons to believe that implementation of the above agreement may have a significant impact on the Issuer's future revenue position.

Signatures of the Company's representatives:

Maciej Adamczyk
MANAGEMENT BOARD MEMBER